NEC

MOS FIELD EFFECT TRANSISTOR
2SK3062

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

This product is N-Channel MOS Field Effect Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3062	TO-220AB
2SK3062-S	TO-262
2SK3062-ZJ	TO-263

FEATURES

- Low on-state resistance
  $R_{DS(on)1}$ = 8.5 mΩ MAX. (V_{GS} = 10 V, I_D = 35 A)
  $R_{DS(on)2}$ = 12 mΩ MAX. (V_{GS} = 4.0 V, I_D = 35 A)
- Low C_{iss}: C_{iss} = 5200 pF TYP.
- Built-in gate protection diode

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	60	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(AC)}$	±20	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(DC)}$	+20, –10	V
Drain Current (DC)	$I_{D(DC)}$	±70	A
Drain Current (Pulse) Note1	$I_{D(pulse)}$	±280	A
Total Power Dissipation (T_C = 25°C)	P_T	100	W
Total Power Dissipation (T_A = 25°C)	P_T	1.5	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C
Single Avalanche Current Note2	I_{AS}	35	A
Single Avalanche Energy Note2	E_{AS}	122.5	mJ

Notes 1. PW ≤ 10 μs, Duty cycle ≤ 1 %

2. Starting Tch = 25 °C, R_G = 25 Ω, V_{GS} = 20 V → 0 V

THERMAL RESISTANCE

Channel to Case	$R_{th(ch-C)}$	1.25	°C/W
Channel to Ambient	$R_{th(ch-A)}$	83.3	°C/W

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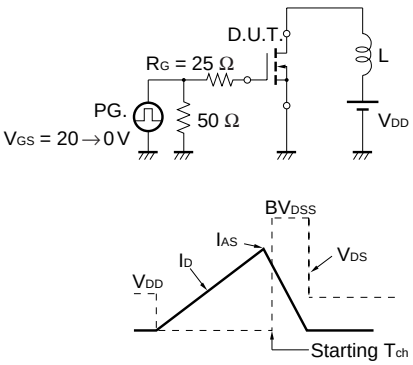
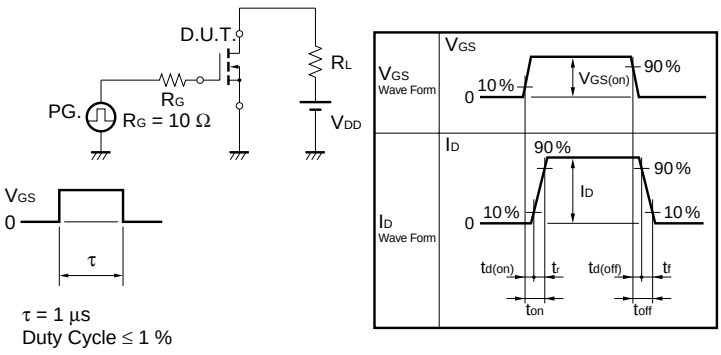
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 35 A		6.3	8.5	mΩ
	$R_{DS(on)2}$	V_{GS} = 4.0 V, I_D = 35 A		8.2	12	mΩ
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	1.0	1.5	2.0	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D = 35 A	20	87		S
Drain Leakage Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			10	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V			±10	μA
Input Capacitance	C_{iss}	V_{DS} = 10 V		5200		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		1300		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		480		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = 35 A		75		ns
Rise Time	t_r	$V_{GS(on)}$ = 10 V		1150		ns
Turn-off Delay Time	$t_{d(off)}$	V_{DD} = 30 V		360		ns
Fall Time	t_f	R_G = 10 Ω		480		ns
Total Gate Charge	Q_G	I_D = 70 A		95		nC
Gate to Source Charge	Q_{GS}	V_{DD} = 48 V		13		nC
Gate to Drain Charge	Q_{GD}	$V_{GS(on)}$ = 10 V		30		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 70 A, V_{GS} = 0 V		0.97		V
Reverse Recovery Time	t_{rr}	I_F = 70 A, V_{GS} = 0 V		70		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A/μs		140		nC

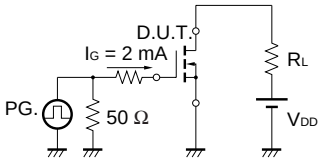
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME

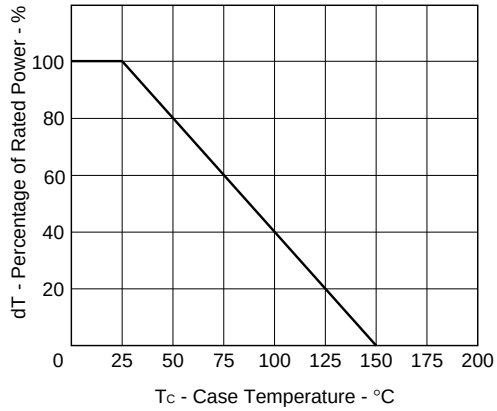


TEST CIRCUIT 3 GATE CHARGE

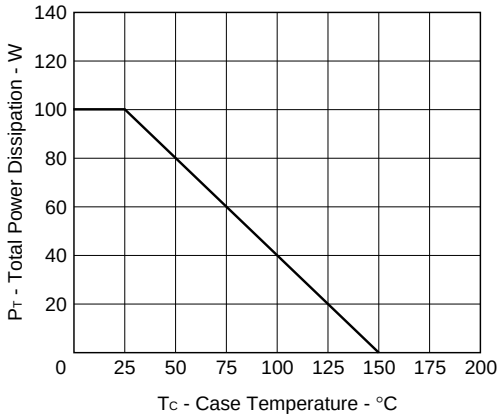


TYPICAL CHARACTERISTICS (T_A = 25 °C)

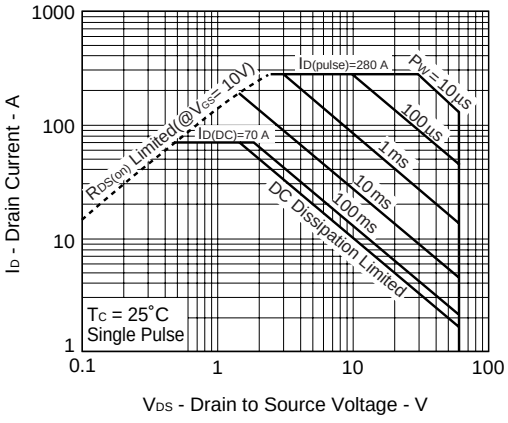
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



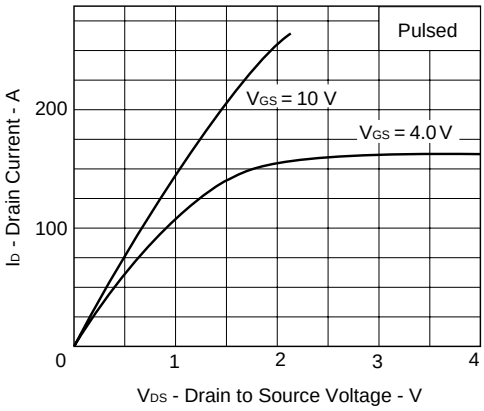
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



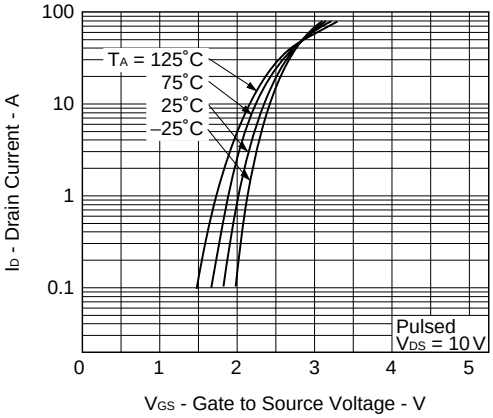
FORWARD BIAS SAFE OPERATING AREA



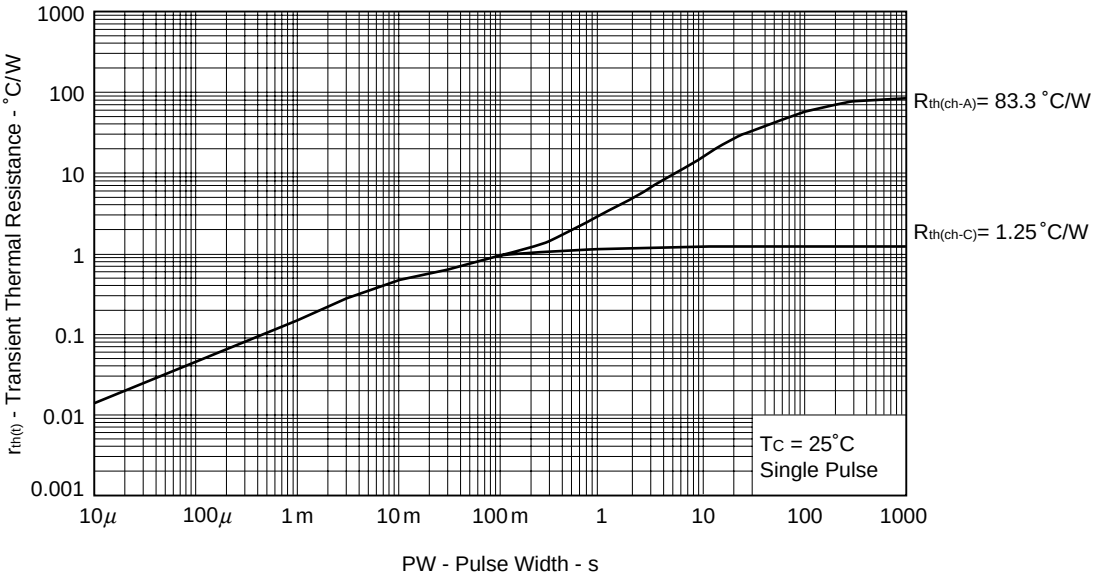
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



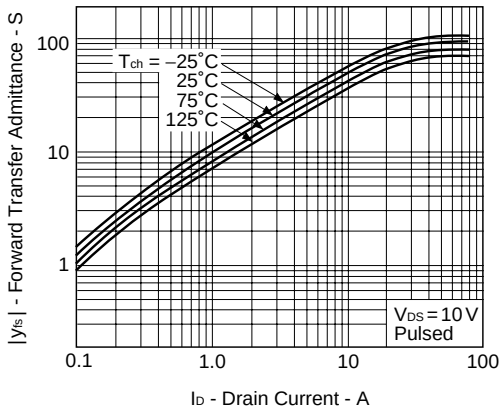
FORWARD TRANSFER CHARACTERISTICS



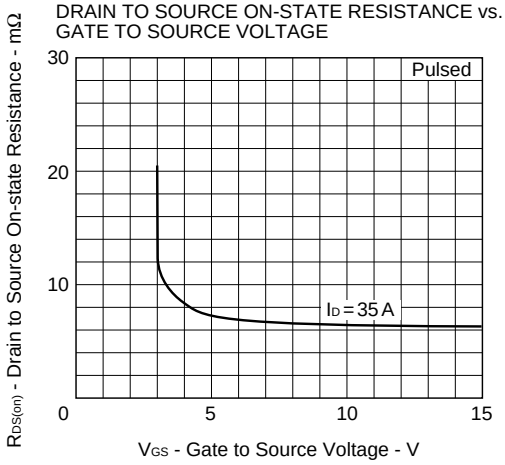
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



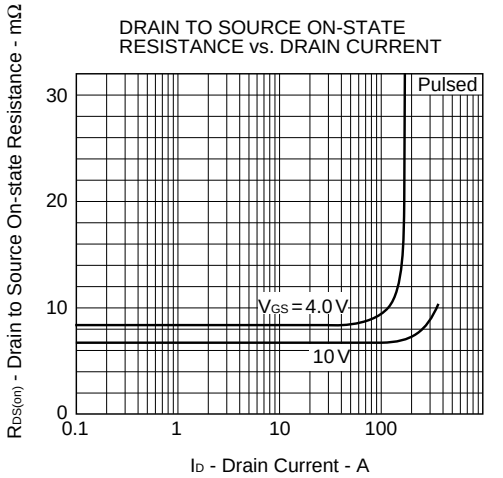
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



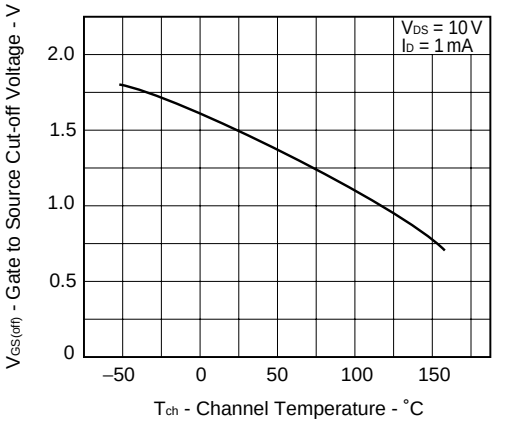
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



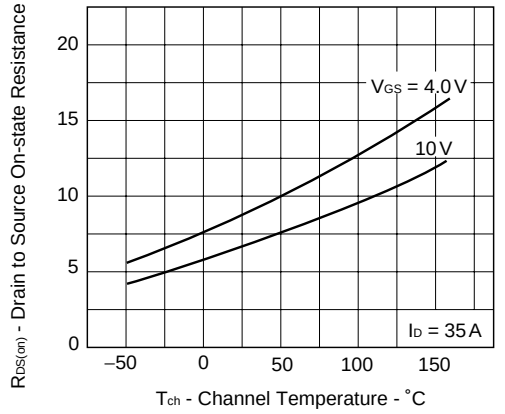
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



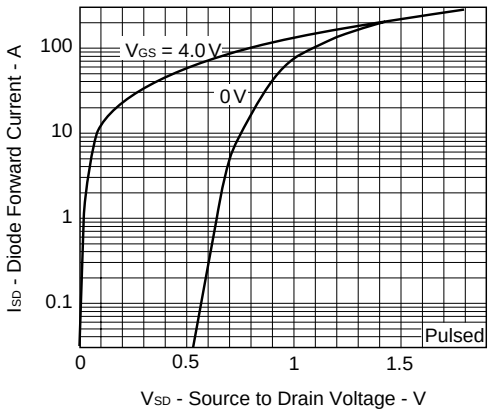
GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



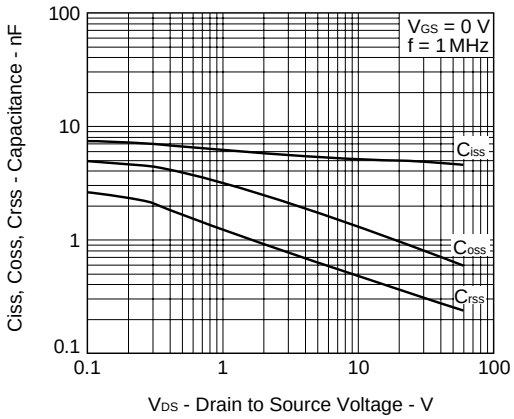
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



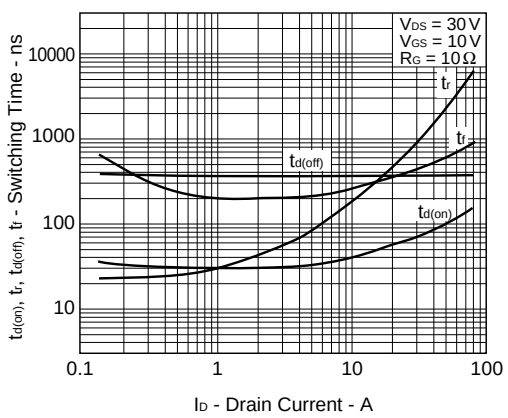
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



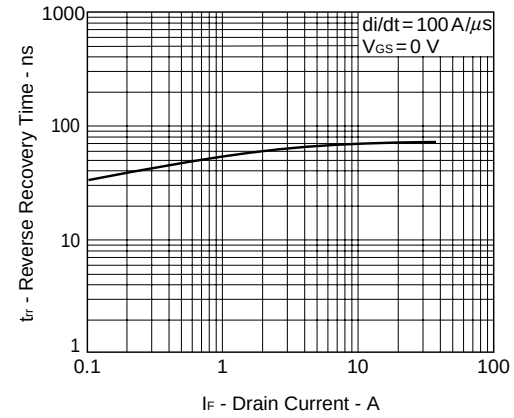
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



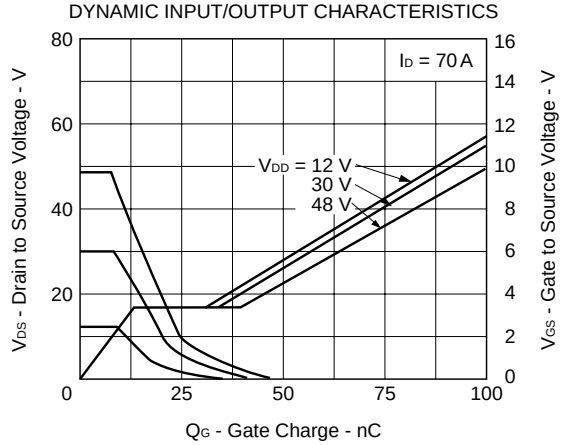
SWITCHING CHARACTERISTICS



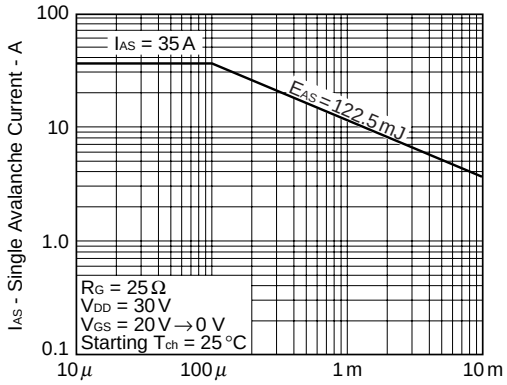
REVERSE RECOVERY TIME vs. DRAIN CURRENT



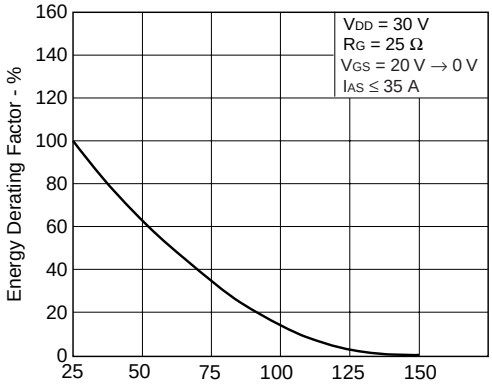
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SINGLE AVALANCHE CURRENT vs.
INDUCTIVE LOAD

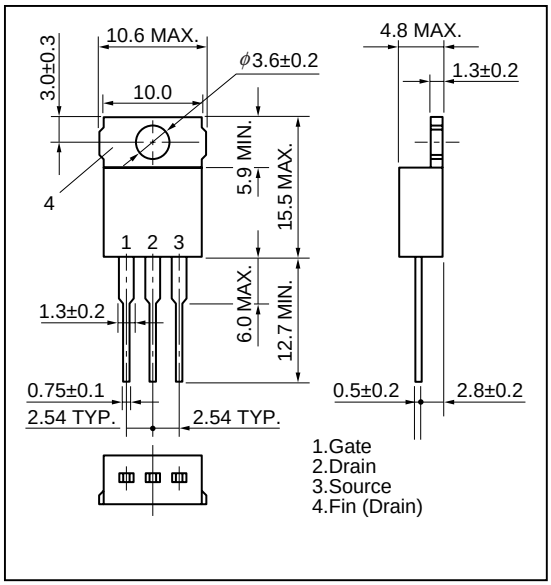


SINGLE AVALANCHE ENERGY
DERATING FACTOR

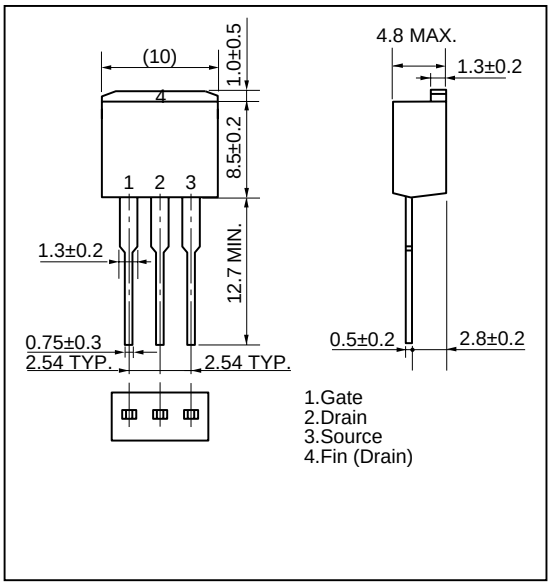


PACKAGE DRAWINGS (Unit : mm)

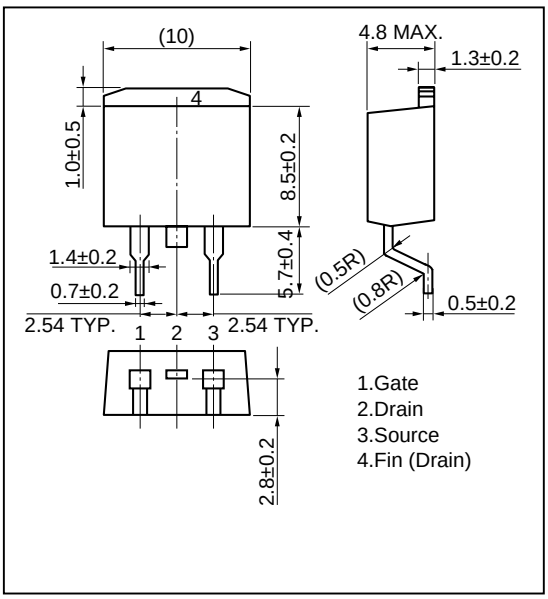
1)TO-220AB (MP-25)



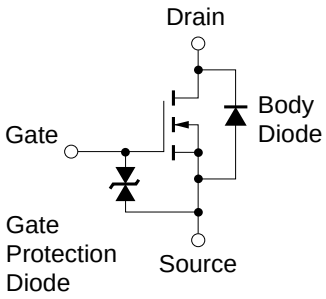
2)TO-262 (MP-25 Fin Cut)



3)TO-263 (MP-25ZJ)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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